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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Christo P. Bojkov, et al.

Art Unit: Not Assigned

Serial No.: 10/086,117

Examiner: Not Assigned

Filed: 02/26/02

Docket: TI-33887

For: Waferlevel Method for Direct Bumping on Copper Pads in Integrated Circuits

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)  
I hereby certify that the above correspondence is being deposited  
with the U.S. Postal Service on 6-5-02  
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Assistant Commissioner for  
Patents  
Washington, D. C. 20231

Karen Vertz 6-5-02  
Karen Vertz Date

PRELIMINARY AMENDMENT

Dear Sir:

This application claims priority under 35 USC 119 (e)(1) of provisional application number  
60/342,949, filed 12/21/01.

Please amend the specification by inserting before the first line the sentence:

--This application claims priority under 35 USC § 119 (e) (1) of provisional application  
number 60/342,949 filed 12/21/01.--

Should the Examiner have any further comments or suggestions, it is respectfully  
requested that the Examiner contact the undersigned in order to expeditiously resolve any  
outstanding issues.

Texas Instruments Incorporated  
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Respectfully submitted,

Gary C. Honeycutt  
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